

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	flexible near (leadframe\$1 (lead near frame\$1)) with (embed\$3 near (circuit chip die component))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/09 11:34
L2	56	(leadframe\$1 (lead near frame\$1)) with (embed\$3 near (circuit chip die component))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/09 11:58
L3	385	(leadframe\$1 (lead near frame\$1)) and (embed\$3 near (circuit chip die component))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/09 11:33
L4	4	(flexible near (leadframe\$1 (lead near frame\$1))) and (embed\$3 near (circuit chip die component))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/09 11:34
L5	119	3 and flexible	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/09 11:41
L6	1	(leadframe\$1 (lead near frame\$1)) with (embed\$3 near IC)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/09 11:59
L7	1	(leadframe\$1 (lead near frame\$1)) with (embed\$3 near ((signal near filter\$1) (tun\$3 near capcitor\$1) inductor\$1 IC))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/11/09 12:01
L8	0	((thermal heat) near spreader\$1) AND (leadframe\$1 (lead near frame\$1)) AND (embed\$3 near ((signal near filter\$1) (tun\$3 near capcitor\$1) inductor\$1 IC)) AND (flexible near insulat\$3) AND ((conduct\$3 metal) near (trace\$1 path\$1 wir\$3)).CLM.	US-PGPUB; USPAT	OR	ON	2005/11/09 12:04
L9	1	((thermal heat) near spreader\$1) AND (leadframe\$1 (lead near frame\$1)) AND (embed\$3 near (circuit chip die component IC)) AND (flexible near insulat\$3) AND ((conduct\$3 metal) near (trace\$1 path\$1 wir\$3)).CLM.	US-PGPUB; USPAT	OR	ON	2005/11/09 12:05